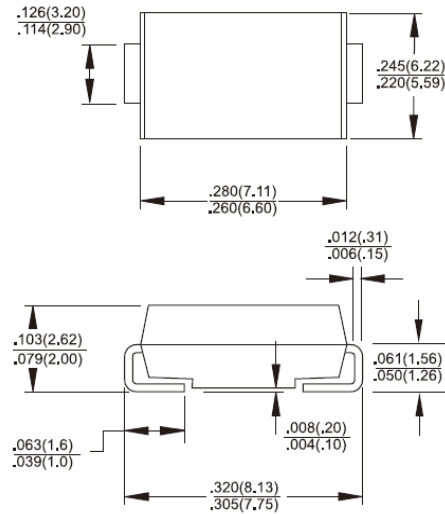



SMC/DO-214AB

Features

- ✧ For surface mounted application
- ✧ Glass passivated junction chip
- ✧ Built-in strain relief, ideal for automated placement
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering: 260°C / 10 seconds at terminals
- ✧ Green compound with suffix "G" on packing code & prefix "G" on datecode

Mechanical Data

- ✧ Case: Molded plastic
- ✧ Terminals: Pure tin plated, Lead free
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 16mm tape per EIA STD RS-481
- ✧ Weight: 0.21 grams

Dimensions in inches and (millimeters)
Marking Diagram


- RS3X = Specific Device Code
- G = Green Compound
- Y = Year
- M = Work Month

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

| Type Number | Symbol | RS 3A | RS 3B | RS 3D | RS 3G | RS 3J | RS 3K | RS 3M | Unit |
|--|------------------------------------|---------------|-------|-------|-------|-------|-------|-------|--------------------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current @ $T_L=75^\circ\text{C}$ | $I_{F(AV)}$ | 3 | | | | | | | A |
| Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) | I_{FSM} | 100 | | | | | | | A |
| Maximum Instantaneous Forward Voltage (Note 1) @ 3 A | V_F | 1.3 | | | | | | | V |
| Maximum Reverse Current @ Rated VR $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$ | I_R | 10 250 | | | | | | | uA |
| Maximum Reverse Recovery Time (Note 2) | T_{rr} | 150 | | | 250 | 500 | | nS | |
| Typical Junction Capacitance (Note 3) | C_j | 60 | | | | | | | pF |
| Typical Thermal Resistance | $R_{\theta JA}$ $R_{\theta JL}$ | 50 15 | | | | | | | $^\circ\text{C/W}$ |
| Operating Temperature Range | T_J | - 55 to + 150 | | | | | | | $^\circ\text{C}$ |
| Storage Temperature Range | T_{STG} | - 55 to + 150 | | | | | | | $^\circ\text{C}$ |

Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

Note 2: Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Note 3: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

RATINGS AND CHARACTERISTIC CURVES (RS3A THRU RS3M)

FIG.1 FORWARD CURRENT DERATING CURVE

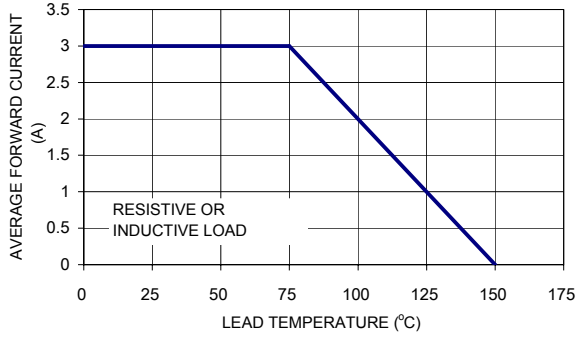


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

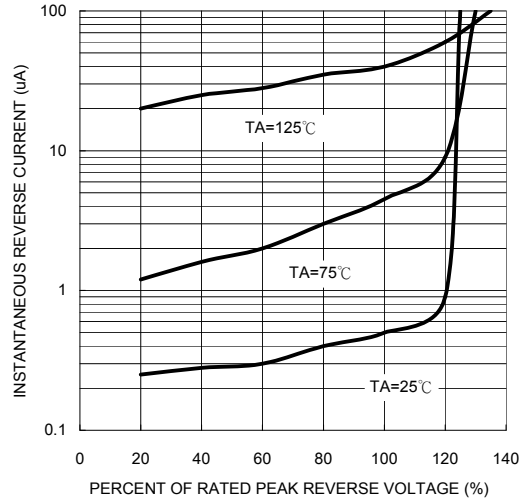


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

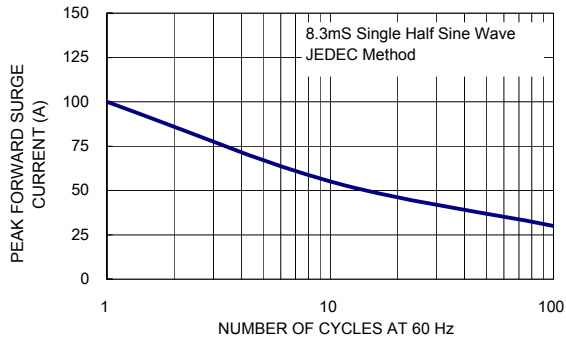


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

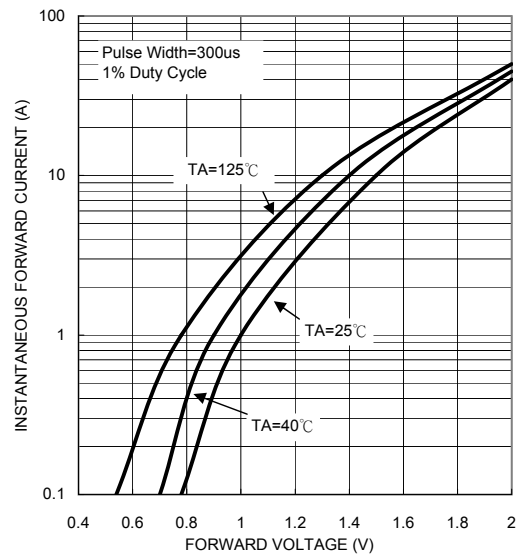


FIG. 4 TYPICAL JUNCTION CAPACITANCE

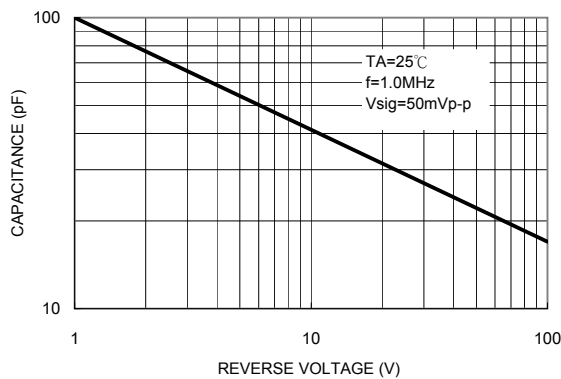


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

